

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Y. SAITOH et al.
Serial No.: (new continuation application under 37 CFR §1.53[b] of
U.S. Application Serial No. 09/906,060)
Filed: January 27, 2004
For: SEMICONDUCTOR WAFER, SEMICONDUCTOR CHIP,
AND MANUFACTURING METHOD OF
SEMICONDUCTOR DEVICE
Group: 2818
Examiner: T. NGUYEN

CLAIM FOR FOREIGN PRIORITY

MS: PATENT APPLICATIONS

Commissioner for Patents
POB 1450
Alexandria, VA 22313-1450

January 27, 2004

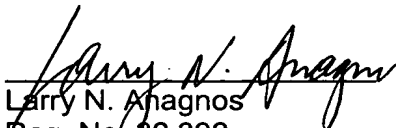
Sir:

Pursuant to 35 U.S.C. §119 and 37 CFR §1.55, applicants hereby claim
the right of priority based on the following foreign application filed in Japan:

Application No. 2000-218234, filed July 19, 2000.

A certified copy of this foreign application was filed on July 17, 2001
in U. S. application Serial No. 09/906,060.

Respectfully submitted,
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